




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-15
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement		
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Legal Statement		
Supplier Acceptance *	true	Legal Declaration * Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>	

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*UY16CFA	A	BO2A	2018-01-15
Amount	UoM	Unit type	ST ECOPACK Grade	
34.89	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3x4.4x1.0	8	gull wing	
Comment	Package: 6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for TSX393IPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KD6P*UY16CFA				500000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.847	mg	supplier	die	Silicon (Si)	7440-21-3		0.822	mg	970484	23560
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2361	57
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	16529	401
Leadframe	M-004 Copper and its alloys	14.690	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.009	mg	10626	258
				supplier	alloy	Copper (Cu)	7440-50-8		13.991	mg	952417	401003
				supplier	alloy	Nickel (Ni)	7440-02-0		0.436	mg	29680	12496
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.022	mg	1498	631
				supplier	alloy	Silicon (Si)	7440-21-3		0.095	mg	6467	2723
				supplier	metalization	Nickel (Ni)	7440-02-0		0.133	mg	9054	3812
Die attach	M-008 Precious metals	0.338	mg	supplier	metalization	Palladium (Pd)	7440-05-3		0.009	mg	613	258
				supplier	metalization	Gold (Au)	7440-57-5		0.004	mg	272	115
				supplier	glue	Silver (Ag)	7440-22-4		0.297	mg	878698	8512
Bonding wires	M-011 Other inorganic materials	0.036	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.017	mg	50296	487
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.017	mg	50296	487
				supplier	glue	Acrylate polymer	87320-05-6		0.007	mg	20710	201
				supplier	wire	Copper (Cu)	7440-50-8		0.036	mg	1000000	1032
Encapsulation	M-015 Other organic materials	18.979	mg	supplier	mold compound	Silica, vitreous	60676-86-0		16.645	mg	877022	477071
				supplier	mold compound	Epoxy resin	85954-11-6		0.759	mg	39992	21754
				supplier	mold compound	Epoxy	29690-82-2		0.759	mg	39992	21754
				supplier	mold compound	phenol resin	25068-38-6		0.569	mg	29981	16308
				supplier	mold compound	additive	Proprietary		0.190	mg	10011	5446
				supplier	mold compound	carbon black	1333-86-4		0.057	mg	3003	1634